

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Drawing updated to reflect current requirements. - lgt	01-06-13	Raymond Monnin
B	Corrections to table I test conditions and footnote. Editorial changes throughout. - drw	04-06-14	Raymond Monnin

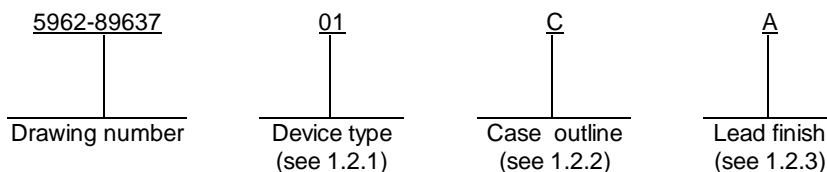
THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.

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REV STATUS	REV	B	B	B	B	B	B	B	B	B	B									
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9										
PMIC N/A	PREPARED BY Rick C. Officer				<b>DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218 <a href="http://www.dscc.dla.mil">http://www.dscc.dla.mil</a></b>  <b>MICROCIRCUIT, LINEAR, WIDEBAND RMS-TO-DC CONVERTER, MONOLITHIC SILICON</b>															
<b>STANDARD MICROCIRCUIT DRAWING</b>  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE  AMSC N/A	CHECKED BY Charles E. Besore																			
	APPROVED BY Michael Frye																			
	DRAWING APPROVAL DATE 90-01-02																			
	REVISION LEVEL B				SIZE A	CAGE CODE <b>67268</b>	<b>5962-89637</b>													
					SHEET 1 OF 9															

1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device type. The device type identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	AD637	Wideband RMS-to-DC converter

1.2.2 Case outline. The case outline is as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
C	GDIP1-T14 or CDIP2-T14	14	Dual-in-line

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings.

Positive supply voltage (+V <sub>S</sub> ) .....	+18 V dc
Negative supply voltage (-V <sub>S</sub> ) .....	-18 V dc
Output short circuit duration .....	Indefinite
Storage temperature range .....	-65°C to +150°C
Lead temperature (soldering, 10 seconds) .....	+300°C
Internal quiescent power dissipation .....	108 mW
Thermal resistance, junction to case (θ <sub>JC</sub> ) .....	See MIL-STD-1835
Thermal resistance, junction to ambient (θ <sub>JA</sub> ) .....	95°C/W
Junction temperature (T <sub>J</sub> ) .....	+175°C

1.4 Recommended operating conditions.

Positive supply voltage (+V <sub>S</sub> ) .....	+15 V dc
Negative supply voltage (-V <sub>S</sub> ) .....	-15 V dc
Ambient operating temperature range (T <sub>A</sub> ) .....	-55°C to +125°C

<b>STANDARD MICROCIRCUIT DRAWING</b> DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>	REVISION LEVEL B	<b>5962-89637</b>  SHEET 2
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## 2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

### DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

### DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.  
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

### DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.  
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or [www.dodssp.daps.mil](http://www.dodssp.daps.mil) or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Functional block diagram. The functional block diagram shall be as specified on figure 2.

3.2.3 Case outline. The case outline shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

3.5.1 Certification/compliance mark. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.

3.9 Verification and review. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

#### 4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
  - (2)  $T_A = +125^\circ\text{C}$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions +V <sub>S</sub> = +15 V, -V <sub>S</sub> = -15 V -55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Total error	E <sub>T</sub>	V <sub>IN</sub> = 0 V to ±10 V	1	01		1/	1/
			2, 3			1/	
Total error versus positive supply	$\frac{\Delta E_T}{\Delta + V_S}$	+5.0 V ≤ +V <sub>S</sub> ≤ +15 V	1, 2, 3	01		±150	μV/V
Total error versus negative supply	$\frac{\Delta E_T}{\Delta - V_S}$	-5.0 V ≤ -V <sub>S</sub> ≤ -15 V	1	01		±300	μV/V
			2			±500	
DC reversal error	E <sub>TR</sub>	V <sub>IN</sub> = ±2.0 V, T <sub>A</sub> = +25°C	1	01		±.25	% of reading
2.0 V fullscale nonlinearity	NL <sub>1</sub>	10 mV ≤  V <sub>IN</sub>   ≤ 2.0 V	1	01		±.04	% of FS
			2, 3			±.06	
7.0 V fullscale nonlinearity	NL <sub>2</sub>	10 mV ≤  V <sub>IN</sub>   ≤ 7.0 V	1	01		±.05	% of FS
			2, 3			±.14	
Output offset voltage	V <sub>OSO</sub>	V <sub>IN</sub> = GND	1	01		±1.0	mV
			2, 3			±6.0	
Output offset voltage temperature coefficient	$\frac{\Delta V_{OSO}}{\Delta T}$	V <sub>IN</sub> = GND	2, 3	01		±.07	mV/°C
Output voltage swing at RMS OUT	V <sub>OP</sub>	R <sub>L</sub> = 2.0 kΩ	1, 2, 3	01	12		V
I <sub>REF0</sub> <u>2/</u> for 0 dB = 1.0 V rms	I <sub>REF1</sub>	T <sub>A</sub> = 25°C	1	01	5.0	80	μA
I <sub>REF</sub> range <u>2/</u>	I <sub>REF2</sub>	T <sub>A</sub> = 25°C	1	01	1.0	100	μA
Buffer input offset voltage	V <sub>OS2</sub>	T <sub>A</sub> = 25°C	1	01		±2.0	mV
Buffer input current	I <sub>IN</sub>	T <sub>A</sub> = 25°C	1	01		±10	nA
Denominator input resistance <u>2/</u>	R <sub>DEN</sub>	T <sub>A</sub> = 25°C	4	01	20	30	kΩ
Denominator input offset voltage <u>2/</u>	V <sub>OS3</sub>	T <sub>A</sub> = 25°C	1	01		±0.5	mV
Power supply range	V <sub>S</sub>	T <sub>A</sub> = 25°C	1	01	±3.0	±18	V
Quiescent current	I <sub>Q</sub>	V <sub>S</sub> = ±18 V	1, 2, 3	01		3.0	mA
Standby current	I <sub>SB</sub>	V <sub>CS</sub> ≤ 0.2 V, T <sub>A</sub> = +25°C	1	01		450	μA

1/ For subgroup 1, the maximum total error is ±1.0 mV ±0.5% of reading. For subgroup 2 and 3, the maximum total error is ±6.0 mV ±0.7% of reading. Total error represents the maximum deviation of the dc component of the output voltage from the theoretical output value over a specified range of signal amplitude and frequency. It is shown as the sum of a fixed error and a component proportional to the theoretical output (percentage of reading). The fixed error component includes all offset errors and irreducible nonlinearities; the percentage of reading component includes the linear scale-factor error.

2/ If not tested, shall be guaranteed to the limits specified in table I.

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Device type	01
Case outline	C
Terminal number	Terminal symbol
1	BUF IN
2	NC
3	COMMON
4	OFFSET NULL
5	$\overline{CS}$
6	$V_{REF}$
7	dB
8	$C_{AVG}$
9	RMS OUT
10	$-V_S$
11	$+V_S$
12	NC
13	$V_{IN}$
14	BUF OUT

NC = No connection

FIGURE 1. Terminal connections.

<b>STANDARD MICROCIRCUIT DRAWING</b> DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-89637</b>
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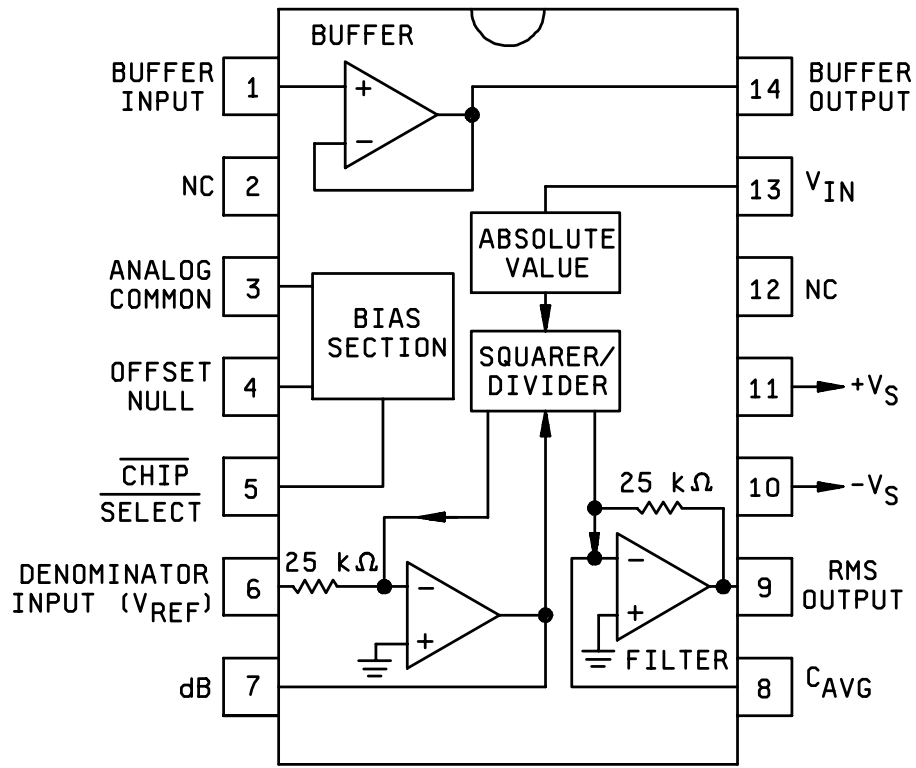


FIGURE 2. Functional block diagram.

<b>STANDARD MICROCIRCUIT DRAWING</b> DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-89637</b>
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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3
Group A test requirements (method 5005)	1, 2, 3, 4**
Groups C and D end-point electrical parameters (method 5005)	1

\* PDA applies to subgroup 1.

\*\* Subgroups 4, if not tested shall be guaranteed to the limits specified in table I herein.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5, 6, 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}\text{C}$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0547.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 04-06-14

Approved sources of supply for SMD 5962-89637 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-8963701CA	24355	AD637SQ/883B

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE  
number

24355

Vendor name  
and address

Analog Devices, Inc.  
Rt. 1 Industrial Park  
P.O. Box 9106  
Norwood, Ma. 02062

Point of Contact:

804 Woburn Street  
Wilmington, MA 01887-3462

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